

CLAIMS:

1. A method of producing a model or tool comprising
 - (a) building an assembly of substrates by assembling and adhering a substrate to another substrate with a layer of adhesive paste, preferably building a stack assembly of substrates adhered with several intermediate layers of adhesive paste,
 - (b) optionally machining the assembly of substrates,
 - (c) covering the outer surface of the assembly of substrates with a continuous layer of curable paste preferably machine dispensed, and
 - (d) optionally after cure, machining to the final structure, preferably according to a computer design, wherein the composition of the curable paste of step (c) is the same as the composition of at least one of the adhesive paste layers of step (a).
2. The method as claimed in claim 1, comprising machine mixing at least 2 separate components to form the curable and adhesive paste.
3. The method as claimed in any preceding claim, wherein the curable and adhesive paste is thixotropic and has non-slump properties.
4. The method as claimed in any preceding claim wherein the curable and adhesive paste has a dynamic viscosity equal to or less than 10,000 mPa s measured at 25°C.
5. The method as claimed in any preceding claim, wherein the curable paste is an epoxy paste obtained by mixing an epoxy component and a hardener component.
6. The method as claimed in any preceding claim, wherein the curable paste comprises an epoxy component containing a curable epoxy resin and a

hardener component containing a latent or semi-latent hardener.

7. A method of producing a model or tool comprising the sequential steps of:
mixing 2 components to form a curable paste, a first component containing a
5 curable resin, preferably a curable epoxy resin, and a second component
containing a hardener system, which contains a latent or semi latent
hardener,
applying the paste on the outer surface of a substructure in the form of a
continuous layer, curing the continuous layer of paste, machining said cured
10 layer to the desired contour.
8. The method as claimed in any preceding claim, wherein the curable paste
comprises:
(1) an epoxy resin;
15 (2) a thixotropic agent, preferably in an amount sufficient to induce
thixotropic properties; and
(3) a hardener system comprising (a) at least one polyethyleneimine, (b) at
least one other amine having at least two amino hydrogen groups and (c) at
least one other epoxy curative having latent reactivity (requiring heat to fully
20 react), the combined amounts of (a),(b) and (c) being sufficient to effect cure
of the epoxy resin.
9. The method of claim 6 or 7, wherein the latent or semi-latent hardener (3)
comprises any slow reacting epoxy curative which cures slowly or not at all
25 at normal ambient temperature requiring heat to cause full reaction and
preferably contains Diethyl toluene diamine, Dicyandiamide, Diphenyl
diamino sulphone, Boron complexes (eg amine-boron, or alkoxide-boron
complexes), and/or imidazoles.
10. The method as claimed in any preceding claim, wherein the cured paste as a
Heat Deflection Temperature above 100C, preferably above 140C, more
- 30

preferably above 150C .

11. The method as claimed in any preceding claim, wherein the final cured
model or tool is machined to form a tool for production of laminated
5 composites, preferably containing non-halogenated fire retardants.

12. A method of producing a model or tool comprising:

- (a) building an assembly of substrates by assembling and adhering at least
one substrate to another substrate with a layer of adhesive paste,
10 (b) covering the outer surface of the assembly of substrates with a continuous
layer of curable paste, preferably machine dispensed
wherein the composition of the curable paste of step (b) is the same as the
composition of at least one of the adhesive paste layers of step (a) and the
composition of this curable paste comprises epoxy resin, amine hardener and
15 a polyethylenimine compound.

13. A curable composition comprising:

- (1) an epoxy resin;
(2) a thixotropic agent preferably present in an amount sufficient to induce
20 thixotropic properties; and
(3) a hardener system comprising (a) at least one polyethylenimine, (b) at
least one other amine having at least two amino hydrogen groups and (c) at
least one other epoxy curative having latent reactivity (requiring heat to fully
react), the combined amounts of (a),(b) and (c) being sufficient to effect cure
25 of the epoxy resin.